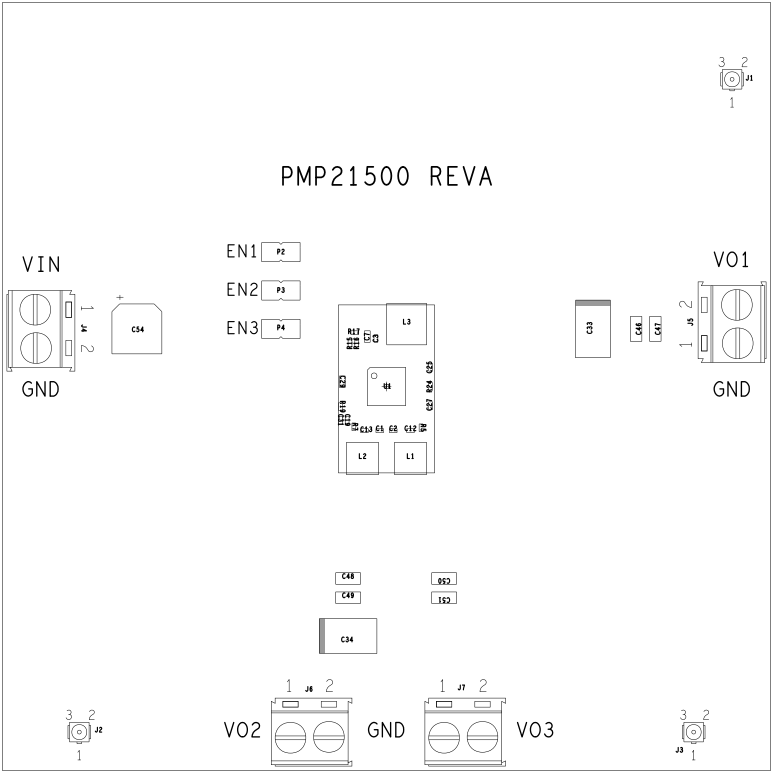
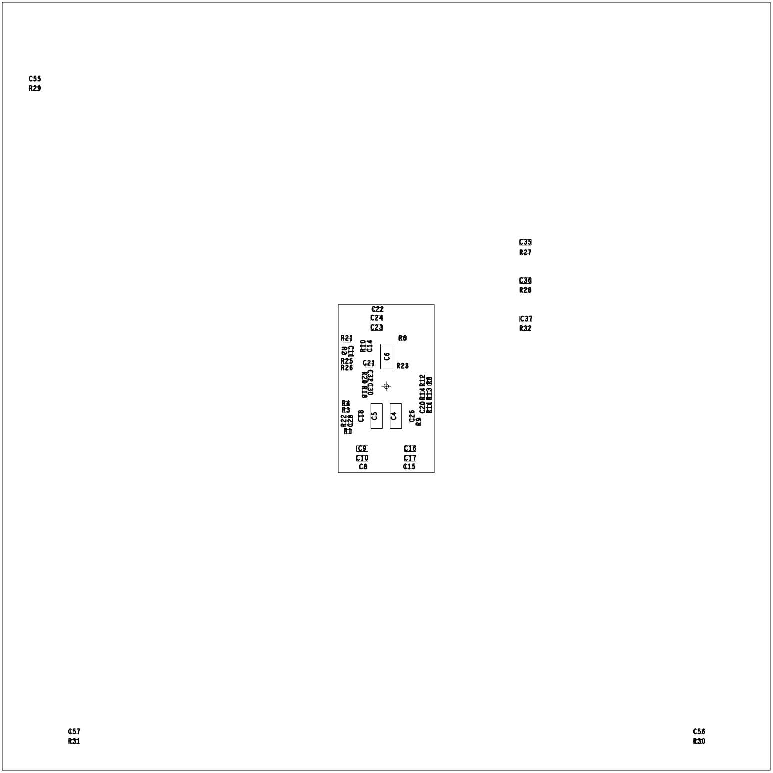

PMP21500 REVA
VIN
J4
GND
C54
EN1
P2
EN2
P3
EN3
P4
L3
R17
R15
R16
C7
C3
U1
C25
R24
C27
C29
R10
C31
C19
R7
C13
C1
C2
C12
R5
L2
L1
C33
C46
C47
VO1
J5
GND
J1
C48
C49
C50
C51
C34
J6
J7
VO2
GND
VO3
J2
J3


C55
R29
C35
R27
C36
R28
C37
R32
C22
C24
C23
R21
R2
C11
R10
C14
R6
C6
R25
R26
C21
R23
R20
C32
R18
C30
R12
R8
R14
R13
C20
R11
R4
R3
R22
C28
C18
C5
C4
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C17
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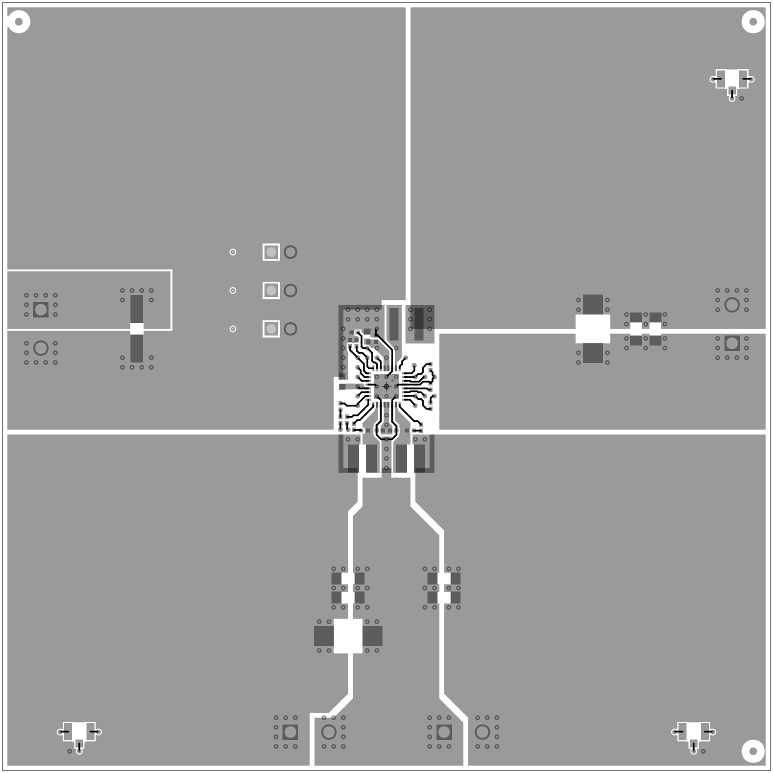
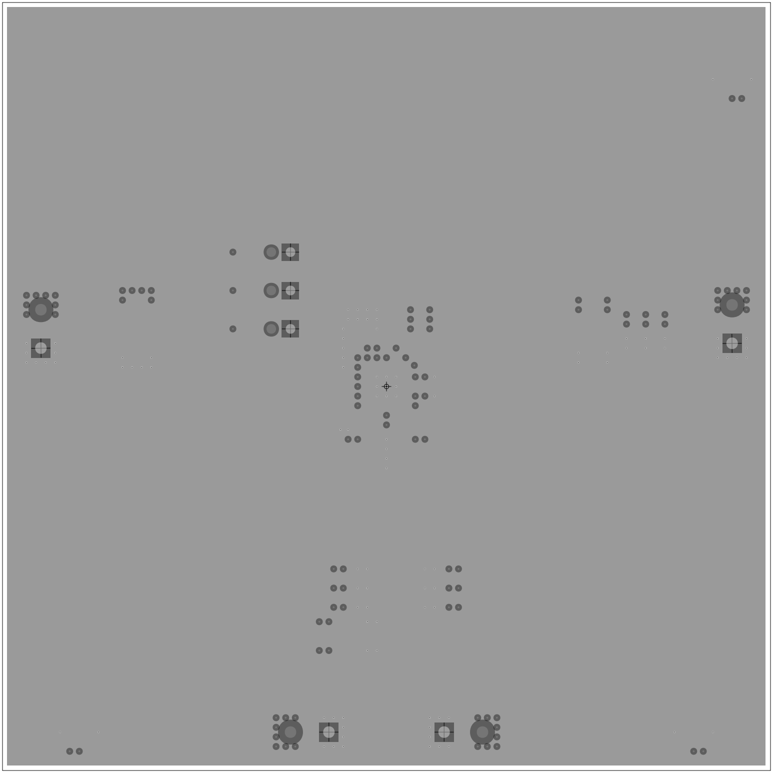
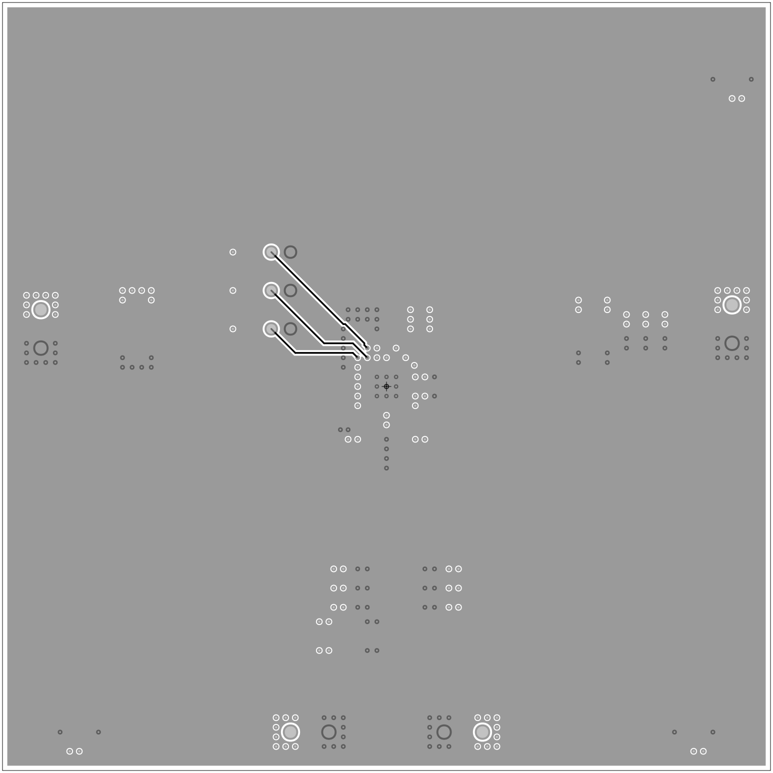
C57
R31
C56
R30



ART FILM - TOP





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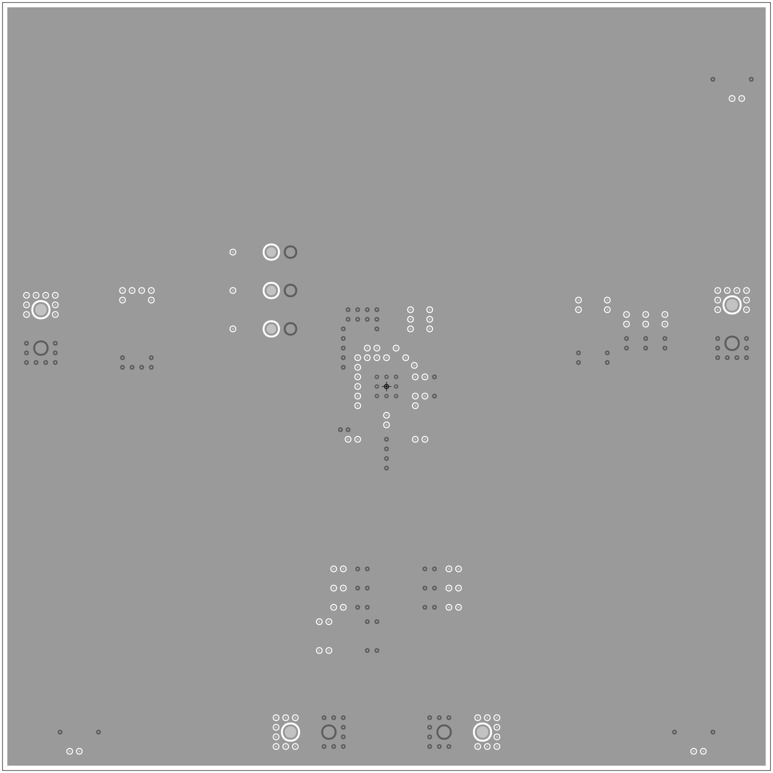
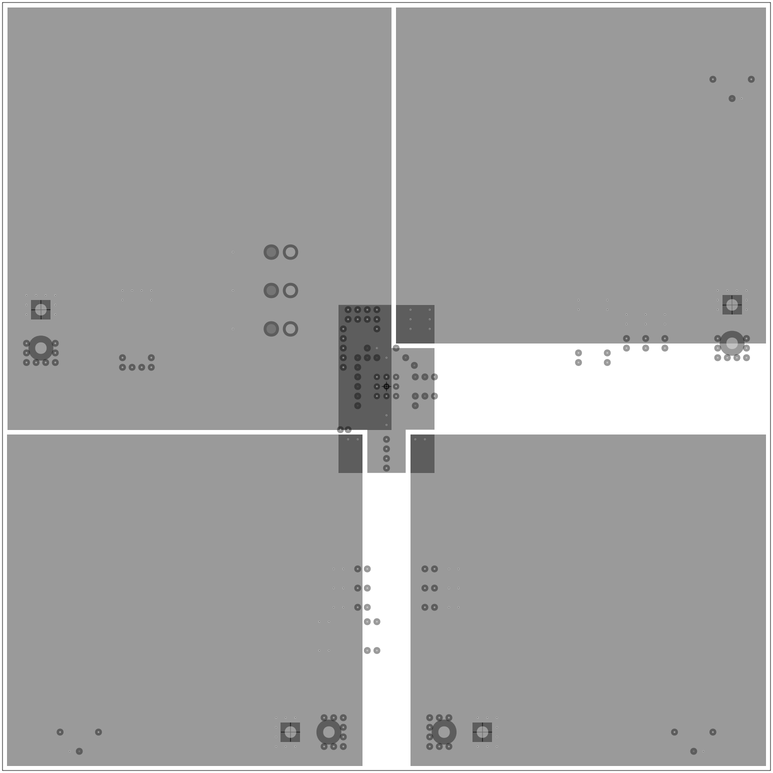
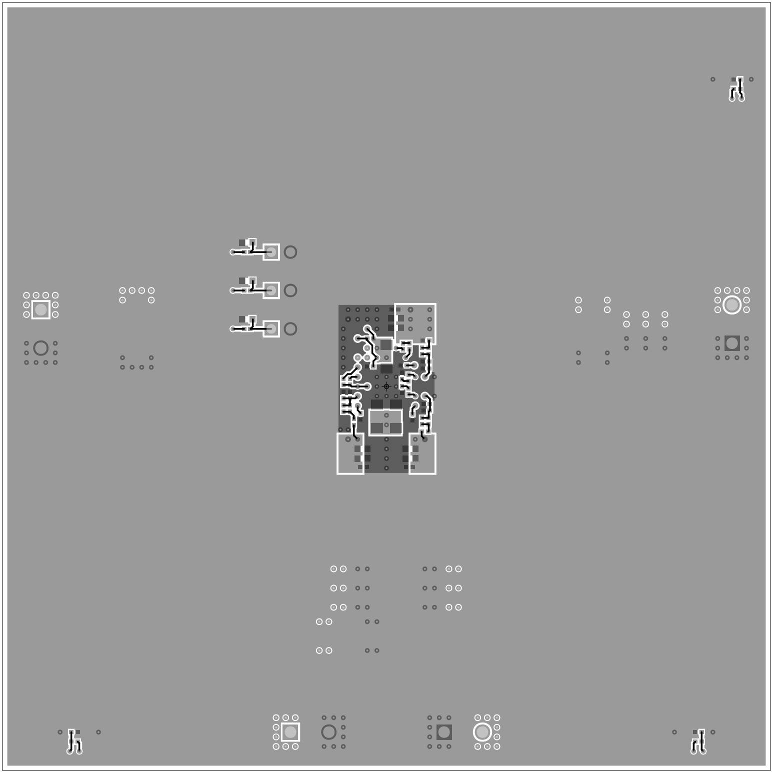
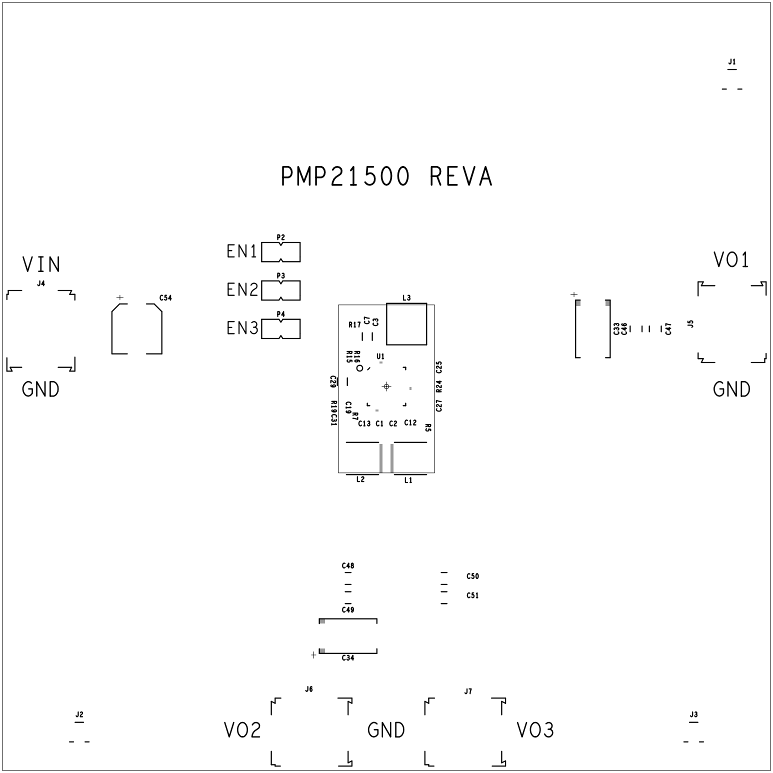




ART FILM - P05



ART FILM - BOTTOM


PMP21500 REVA
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P2
EN1
P3
EN2
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EN3
L3
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C3
R16
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U1
C29
C25
R24
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R7
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C12
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L2
L1
C33
C46
C47
J5
VO1
GND
C48
C49
C50
C51
C34
J6
J7
J2
VO2
GND
VO3
J3


C55
R29
C35
R27
C36
R28
C37
R32
C22
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R6
R10
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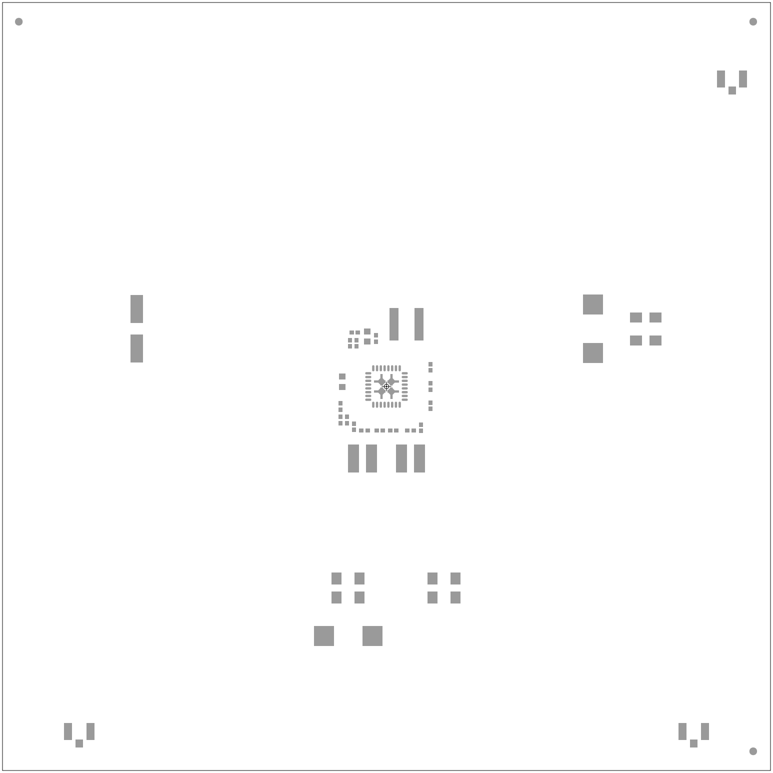
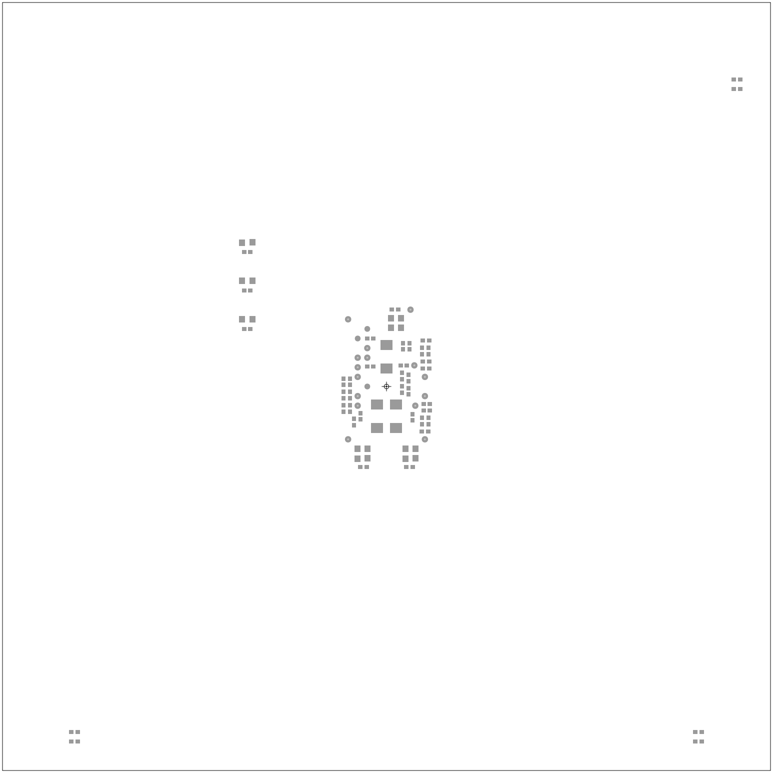
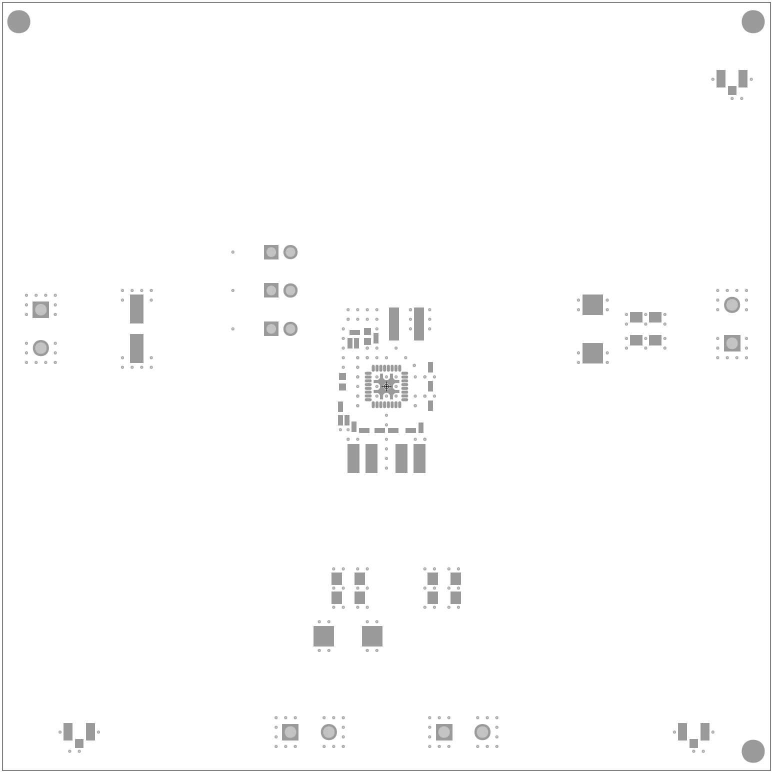
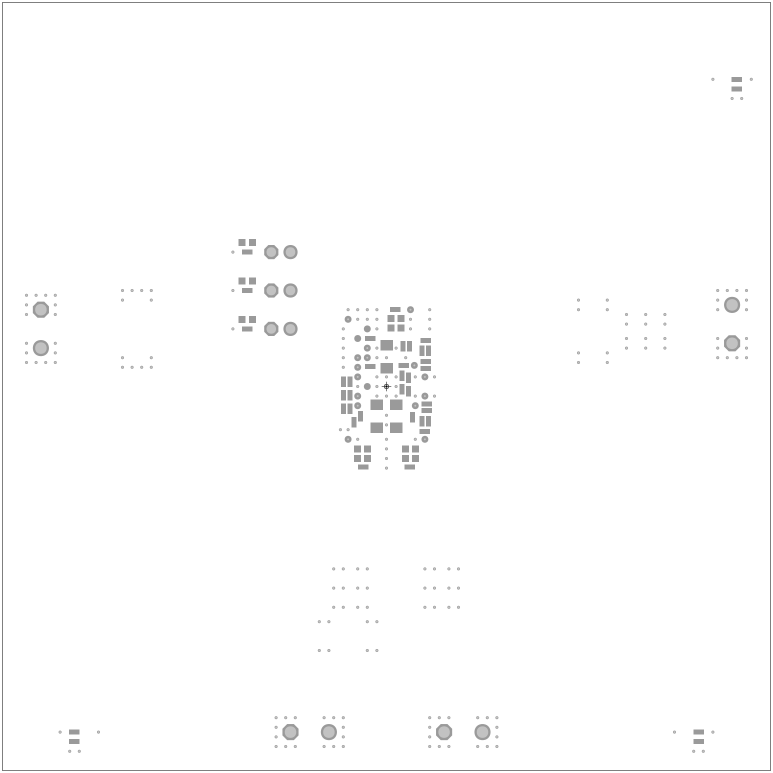
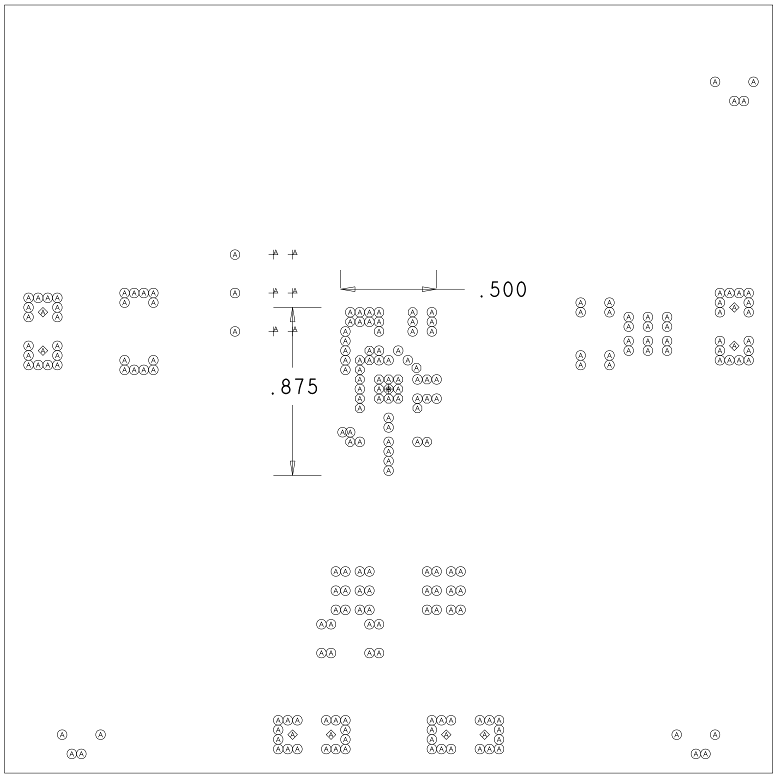
C57
R31









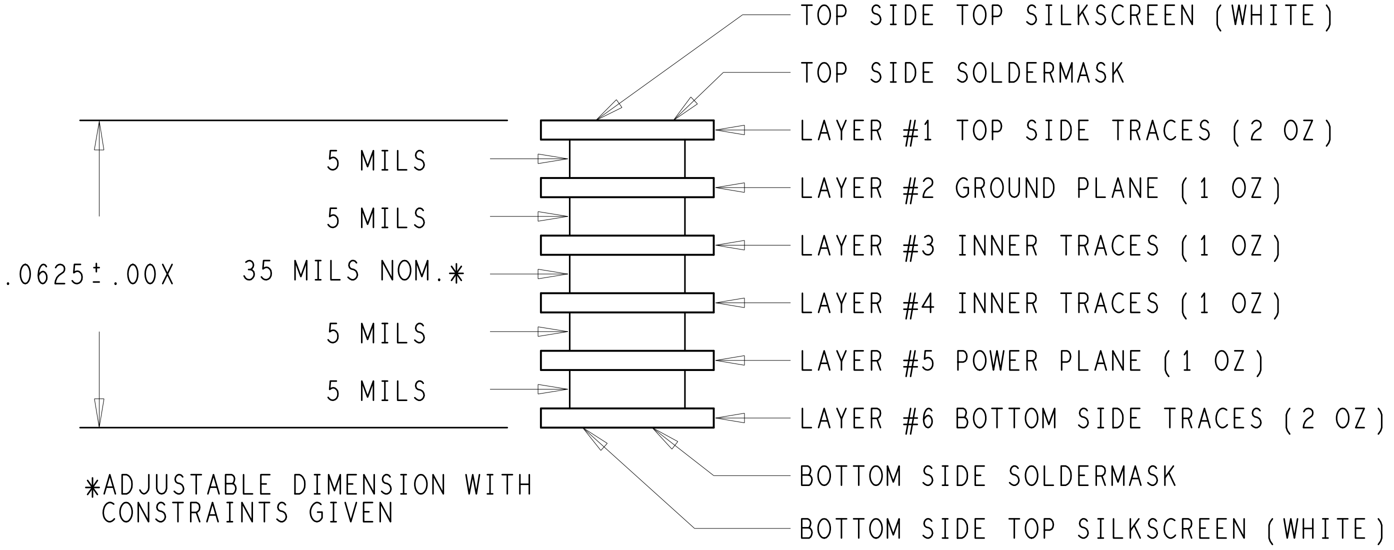


FABRICATION PARAMETERS:

THICKNESS:	0.062
SILKSCREEN:	BOTH
SOLDERMASK:	BOTH
COPPER WEIGHT:	2 OZ (EXT) /1 OZ (INT)
DESIGN TYPE:	MIX
MIN TRACE/GAP:	0.005/0.005
LAYER COUNT:	6 LAYERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL: ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE RoHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0.
2. BASE LAMINATE: PLASTIC SHEET, LAMINATED METAL CLAD, TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 6 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS.
3. SOLDERMASK: SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840.
4. PLATING: HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER.
5. FINISH: PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0005" +/- 0.0003" THICK MIN ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.
6. LEGEND: IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.
7. MARKINGS: BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.
8. WORKMANSHIP: PC BOARD SHALL BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.
9. DOCUMENTATION: PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.
10. DRILL SIZES: HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.
11. PANEL BORDER: ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.
12. PROCESS CHANGES: NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.



VIEW X-X XX

SCALE = NONE

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
Ⓐ	10.0	+2.0/-7.0	PLATED	24
Ⓐ	10.0	+3.0/-3.0	PLATED	181
+	50.0	+3.0/-3.0	PLATED	6
◈	60.0	+3.0/-3.0	PLATED	8

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

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